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Karen Cinq-Mars

(Signature)

(Date)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of _____ :

2002

Mandelman et al. _____ :

Serial No. Unassigned _____ :

Examiner:

Filed: _____ :

IBM Corporation
Dept. 18G/Bldg. 300-482
2070 Route 52
Hopewell Junction,
New York 12533-6531

Title: Backside buried strap
for SOI DRAM trench capacitor _____ :

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents and Trademarks
Washington, D.C. 20231

Sirs:

In compliance with the duty of disclosure under
37 C.F.R. § 1.56 and in accordance with the practice under
37 C.F.R. §§ 1.97 and 1.98, the Examiner's attention is directed to
the documents listed on the enclosed Form PTO-1449. Copies of the
listed documents are also enclosed.

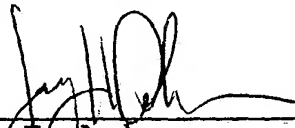
It is respectfully requested that the above information be
considered by the Examiner and that a copy of the enclosed Form
PTO-1449 be returned indicating that such information has been
considered.

Applicants' undersigned attorney may be reached by telephone
at (845) 894-3667. All correspondence should continue to be

directed to the below listed address.

Respectfully submitted,

By


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INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

Docket Number (Optional)

FIS920020038

Application Number

Applicant(s)

Mandelman et al.

Filing Date

Group Art Unit

U.S. PATENT DOCUMENTS

| *EXAMINER INITIAL | REF | DOCUMENT NUMBER | DATE | NAME | CLASS | SUBCLASS | FILING DATE IF APPROPRIATE |
|----------------------|-----|-----------------|----------|--------------------|-------|----------|-------------------------------|
| | | 6,238,967 | 05-29-01 | Shiho et al. | | | |
| | | 6,066,527 | 05-23-00 | Kudelka et al. | | | |
| | | 6,232,170 | 05-15-01 | Hakey et al. | | | |
| | | 6,184,107 | 02-06-01 | Divakaruni et al. | | | |
| | | 6,063,657 | 05-16-00 | Bronner et al. | | | |
| | | 6,204,112 | 03-20-01 | Chakravarti et al. | | | |
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FOREIGN PATENT DOCUMENTS

| | REF | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUBCLASS | Translation | |
|--|-----|-----------------|----------|---------|-------|----------|-------------|----|
| | | | | | | | YES | NO |
| | | WO 00/13225 | 03-09-00 | PCT | | | | |
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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|--|--|--|
| | | "Silicon VLSI Technology Fundamentals, Practice and Modeling" Plummer et al., Department of Electrical Engineering, Stanford University, Prentice Hall Pub., ppgs. 644-647 |
| | | |

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.